

112TH CONGRESS
2D SESSION

H. R. 5422

To extend the temporary suspension of duty on epoxy molding compounds,
of a kind used for encapsulating integrated circuits.

IN THE HOUSE OF REPRESENTATIVES

MAY 7, 2012

Mr. HONDA introduced the following bill; which was referred to the Committee
on Ways and Means

A BILL

To extend the temporary suspension of duty on epoxy molding
compounds, of a kind used for encapsulating integrated
circuits.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

3 **SECTION 1. EPOXY MOLDING COMPOUNDS, OF A KIND**
4 **USED FOR ENCAPSULATING INTEGRATED**
5 **CIRCUITS (PROVIDED FOR IN SUBHEADING**
6 **3907.30.00)).**

7 (a) IN GENERAL.—Heading 9902.01.85 of the Har-
8 monized Tariff Schedule of the United States (relating to
9 epoxy molding compounds, of a kind used for encap-
10 sulating integrated circuits (provided for in subheading

1 3907.30.00)) is amended by striking the date in the effec-
2 tive period column and inserting “12/31/2015”.

3 (b) EFFECTIVE DATE.—The amendment made by
4 subsection (a) applies to goods entered, or withdrawn from
5 warehouse for consumption, on or after the 15th day after
6 the date of the enactment of this Act.

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